



## Materials Declaration Form

<b>IPC</b>	<b>1752</b>	<b>Version</b>	<b>2</b>
<b>Form Type *</b>	<b>Distribute</b>		
<b>Sectionals *</b>	<b>Material Info</b> <b>Manufacturing Info</b>	<b>Subsectionals *</b>	<b>A-D</b>

*\* : Required Field*

Supplier Information			
<b>Company Name *</b>	<b>STMicroelectronics</b>	<b>Response Date *</b>	<b>2020-05-27</b>
<b>Company Unique ID</b>	<b>NL 008751171B01</b>		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	<b>giovanni giacopello</b>	<b>Representative Title</b>	<b>ADG MD CHAMPION</b>
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**

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**Legal Statement**

**Supplier Acceptance \*** **true** **Legal Declaration \*** **Standard**

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
STGB30H60DLLFBAG	XDD2*LW65A52	A	3068	2020-05-27
	Amount	UoM	Unit type	ST ECOPACK Grade
	1380	mg	Each	ECOPACK 1
Comment	ECOPACK® or ECOPACK® 1 is STMicroelectronics trade name for ROHS compliant devices			

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		
1	245	3		
Bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable	Tin (Sn), matte, annealed	Copper Alloy	DM00171277	



Package Designator	Size	Nbr of instances	Shape	
SIP	10.20,9.15,4.50	3	gull wing	
Comment	D2PAK			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-March 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description
7a	Lead in high melting temperature type solders (i.e. lead- based alloys containing 85 % by weight or more lead)

QueryList : ELV directive : 2000/53/EC amended 2017/2096 _November 2017	
Query	Response
1 - Product(s) meets EU ELV requirements without any exemptions	FALSE
2 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	TRUE
Exemption Id.	Description
8e	Lead in high melting temperature type solders (i.e. lead-based alloys containing 85 % by weight or more lead)

QueryList : California Prop65 list, dated 3rd January 2020			
Query			Response
1 - The product does not contain identified substance from California Prop 65 List, no exposure to consumers is foreseen			FALSE
2 - The product is containing below substance(s) from California Prop 65 List, no exposure to consumers is foreseen			TRUE
Substance	amount in product (mg)	Application	ppm in product
Nickel	0.19	die - leadframe	138
Lead	7.25	soft solder	5257
Antimony trioxide	6.96	encapsulation	5043

QueryList : REACH-16th January 2020				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
Lead	1000 ppm	7.25	Soft solder	5257
2 - Product(s) does not contain REACH Substances Of Very High Concern in any Embedded article nor Homogeneous Material above the limits per the definition within REACH				FALSE
CategoryLevel_Name	CategoryLevel_Threshold	Amount in Embedded Article / Homogeneous Material (mg)	Application - Article / Homogeneous Material	ppm in Article /Homogeneous Material
Lead	1000 ppm	7.254	Soft solder	954976

Material Composition Declaration :						Mfr Item Name	XDD2*LW65A52					
note : Substance present with less 0.001mg will not be declared in this document												
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Dies	M-011 Other inorganic materials	8.279	mg	supplier	die	Silicon(Si)	7440-21-3		7.565	mg	913757	5482
				supplier	metallisation	Aluminium(Al)	7429-90-5		0.295	mg	35632	214
				supplier	metallisation	Gold(Au)	7440-57-5		0.005	mg	604	4
				supplier	metallisation	Nicke(Ni)	7440-02-0		0.086	mg	10388	62
				supplier	metallisation	Silver(Ag)	7440-22-4		0.025	mg	3020	18
				supplier	metallisation	Titanium(Ti)	7440-32-6		0.007	mg	846	5
				supplier	metallisation	Vanadium(V)	7440-62-2		0.005	mg	604	4
				supplier	Passivation	Silicon nitride(SiN)	12033-89-5		0.050	mg	6039	36
				supplier	passivation	Silicon oxide	7631-86-9		0.122	mg	14736	88
				supplier	polymer coating	Durimide	proprietary		0.119	mg	14374	86
Leadframe	M-004 Copper and its alloys	778.660	mg	supplier	alloy & coating	Copper(Cu)	7440-50-8		777.532	mg	998551	563429
				supplier	alloy & coating	Nicke(Ni)	7440-02-0		0.105	mg	135	76
				supplier	alloy & coating	Iron(Fe)	7439-89-6		0.358	mg	460	259
				supplier	alloy & coating	Iron Phosphide(FeP)	26508-33-8		0.654	mg	840	474
				supplier	alloy & coating	Phosphorus metal	7723-14-0		0.011	mg	14	8
Soft solder	Solder	7.596	mg	SVHC	solder	Lead(Pb)	7439-92-1	7a-Lead in high melting temper	7.254	mg	954976	5257
				supplier	solder	Silver(Ag)	7440-22-4		0.190	mg	25013	138
				supplier	solder	Tin(Sn)	7440-31-5		0.152	mg	20011	110
Bonding wires	M-003 Aluminum and its alloys	2.894	mg	supplier	wire	Aluminium (Al)	7429-90-5		2.894	mg	1000000	2097
Bonding wires 2	M-003 Aluminum and its alloys	0.137	mg	supplier	wire	Aluminium (Al)	7429-90-5		0.136	mg	992701	99
				supplier	wire	Magnesium (Mg)	7439-95-4		0.001	mg	7299	1
Encapsulation	M-011 Other inorganic materials	579.945	mg	supplier	mold compound	Silica vitreous	60676-86-0		477.295	mg	823002	345866
				supplier	mold compound	Epoxy Cresol Novolac	29690-82-2		40.596	mg	70000	29417
				supplier	mold compound	Phenol resin	9003-35-4		23.198	mg	40000	16810
				supplier	mold compound	Biphenyl epoxy resin	85954-11-6		17.398	mg	29999	12607
				supplier	mold compound	Antimony trioxide	1309-64-4		6.959	mg	11999	5043
				supplier	mold compound	Brominated epoxy resin	40039-93-8		11.599	mg	20000	8405
				supplier	mold compound	Carbon black	1333-86-4		2.900	mg	5000	2101
connections coating	Solder	2.489	mg	supplier	solder alloy	Tin (Sn)	7440-31-5		2.489	mg	1000000	1804